



MOTOROLA

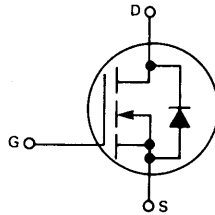
**MTM5N18, MTP5N18
MTM5N20, MTP5N20
MTM7N12, MTP7N12
MTM7N15, MTP7N15**

Designer's Data Sheet

**N-CHANNEL ENHANCEMENT MODE SILICON GATE
TMOS POWER FIELD EFFECT TRANSISTOR**

These TMOS Power FETs are designed for high voltage, high speed power switching applications such as switching regulators, converters, solenoid and relay drivers.

- Silicon Gate for Fast Switching Speeds — Switching Times Specified at 100°C
- Designer's Data — I_{DSS} , $V_{DS(on)}$, $V_{GS(th)}$ and SOA Specified at Elevated Temperature
- Rugged — SOA is Power Dissipation Limited
- Source to Drain Diode Characterized for Use With Inductive Loads



MAXIMUM RATINGS

Rating	Symbol	MTM or MTP				Unit
		7N12	7N15	5N18	5N20	
Drain — Source Voltage	V_{DSS}	120	150	180	200	Vdc
Drain — Gate Voltage ($R_{GS} = 1.0 \text{ M}\Omega$)	V_{DGR}	120	150	180	200	Vdc
Gate — Source Voltage	V_{GS}	± 20				Vdc
Drain Current Continuous Pulsed	I_D	7.0		5.0		Adc
	I_{DM}	18		15		
Gate Current — Pulsed	I_{GM}	1.5				Adc
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	75				Watts
		0.6				
Operating and Storage Temperature Range	T_J, T_{stg}	-65 to 150				$^\circ\text{C}$

THERMAL CHARACTERISTICS

Thermal Resistance Junction to Case	$R_{\theta JC}$	1.67	$^\circ\text{C}/\text{W}$
Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5 seconds	T_L	275	$^\circ\text{C}$

Designer's Data for "Worst Case" Conditions

The Designer's Data Sheet permits the design of most circuits entirely from the information presented. Limit data — representing device characteristics boundaries — are given to facilitate "worst case" design.

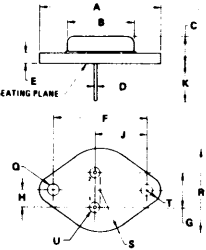
5 and 7 AMPERE

**N-CHANNEL TMOS
POWER FET**

$r'_{DS(on)} = 0.7 \text{ OHM}$
120 and 150 VOLTS

$r'_{DS(on)} = 1.0 \text{ OHM}$
180 and 200 VOLTS

MTM5N18
MTM5N20
MTM7N12
MTM7N15

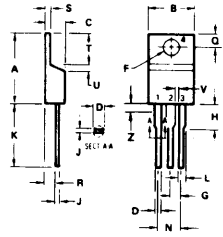


STYLE 3
PIN 1. GATE
2. SOURCE
CASE DRAIN

CASE 1-05
TO-204AA

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	—	26.47	—	1.040
B	—	21.90	—	0.859
C	0.35	7.62	0.250	0.300
D	0.57	1.90	0.020	0.075
E	1.48	1.78	0.055	0.070
F	20.90	30.40	1.177	1.197
G	10.67	11.18	0.420	0.440
H	0.35	5.50	0.210	0.220
J	18.80	17.15	0.855	0.675
K	11.18	12.19	0.440	0.480
L	0.31	4.19	0.150	0.165
M	—	20.97	—	1.050
U	2.54	3.05	0.100	0.120

MTP5N18
MTP5N20
MTP7N12
MTP7N15



STYLE 5
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

CASE 221A-02
TO-220AB

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	15.11	15.75	0.595	0.620
B	9.85	10.29	0.388	0.405
C	4.06	4.82	0.160	0.190
D	0.84	0.75	0.035	0.030
E	3.81	3.73	0.149	0.147
F	2.41	2.87	0.095	0.105
H	2.79	3.30	0.110	0.130
J	0.50	0.58	0.014	0.023
K	12.70	14.27	0.500	0.565
L	1.14	1.27	0.045	0.050
M	4.83	5.33	0.190	0.210
N	2.54	3.04	0.100	0.120
R	2.04	2.78	0.080	0.110
S	1.14	1.29	0.045	0.050
T	5.87	6.48	0.230	0.255
U	0.76	1.27	0.030	0.050
V	1.14	—	0.045	—
Z	—	2.01	—	0.079

DS3555 R1

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ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Drain-Source Breakdown Voltage (V _{GS} = 0, I _D = 5.0 mA)	V _{(BR)DSS}	120 150 180 200	—	Vdc
Zero Gate Voltage Drain Current (V _{DS} = 0.85 Rated V _{DSS} , V _{GS} = 0) (T _J = 100°C)	I _{DSS}	—	0.25 2.5	mAdc
Gate-Body Leakage Current (V _{GS} = 20 Vdc, V _{DS} = 0)	I _{GSS}	—	500	nAdc
ON CHARACTERISTICS*				
Gate Threshold Voltage (I _D = 1.0 mA, V _{DS} = V _{GS}) (T _J = 100°C)	V _{GS(th)}	2.0 1.5	4.5 4.0	Vdc
Static Drain-Source On-Resistance (V _{GS} = 10 Vdc, I _D = 3.5 Adc) (V _{GS} = 10 Vdc, I _D = 2.5 Adc)	r _{DS(on)}	— —	0.7 1.0	Ohms
Drain-Source On-Voltage (V _{GS} = 10 V) (I _D = 7.0 Adc) (I _D = 3.5 Adc, T _J = 100°C) (I _D = 5.0 Adc) (I _D = 2.5 Adc, T _J = 100°C)	V _{DS(on)}	— — — —	5.9 5.0 6.0 5.0	Vdc
Forward Transconductance (V _{DS} = 15 V, I _D = 3.5 A) (V _{DS} = 15 V, I _D = 2.5 A)	g _{fs}	1.5 1.5	— —	mhos

DYNAMIC CHARACTERISTICS

Input Capacitance	(V _{DS} = 25 V, V _{GS} = 0, f = 1.0 MHz)	C _{iss}	—	400	pF
Output Capacitance		C _{oss}	—	175	pF
Reverse Transfer Capacitance		C _{rss}	—	30	pF

SWITCHING CHARACTERISTICS* (T_J = 100°C)

Turn-On Delay Time	(V _{DS} = 25 V, I _D = 0.5 Rated I _D , R _{gen} = 50 ohms, See Figures 1 and 2)	t _{d(on)}	—	20	ns
Rise Time		t _r	—	150	ns
Turn-Off Delay Time		t _{d(off)}	—	50	ns
Fall Time		t _f	—	50	ns

SOURCE DRAIN DIODE CHARACTERISTICS*

Characteristic	Symbol	Typ	Unit
Forward On-Voltage (I _S = Rated I _D)	V _{SD}	2.0	Vdc
Forward Turn-On Time (V _{GS} = 0)	t _{on}	200	ns
Reverse Recovery Time (See Figures 18 and 19)	t _{rr}	300	ns

*Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.

FIGURE 1 – SWITCHING TEST CIRCUIT

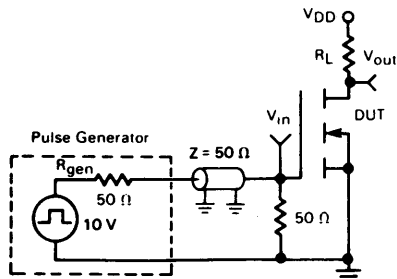
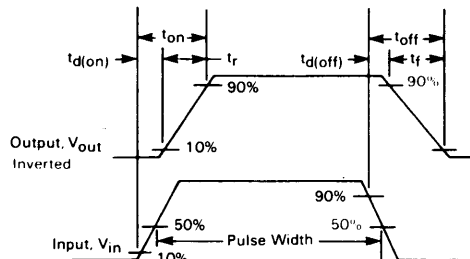


FIGURE 2 – SWITCHING WAVEFORMS



TYPICAL CHARACTERISTICS

ON-REGION CHARACTERISTICS

FIGURE 3 — MTM5N18, MTM5N20
MTP5N18, MTP5N20

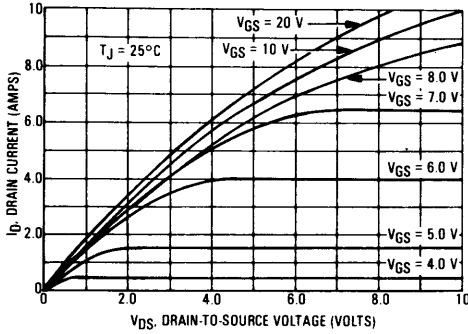
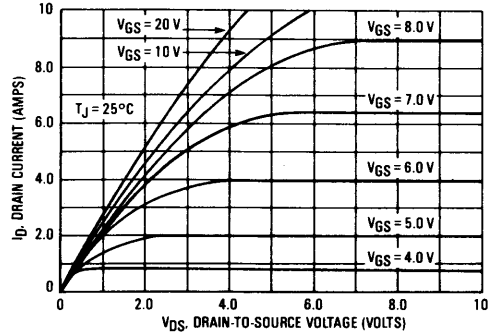


FIGURE 4 — MTM7N12, MTM7N15
MTP7N12, MTP7N15



TRANSFER CHARACTERISTICS

FIGURE 5 — MTM5N18, MTM5N20
MTP5N18, MTP5N20

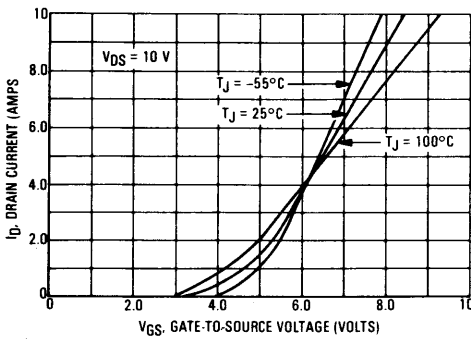
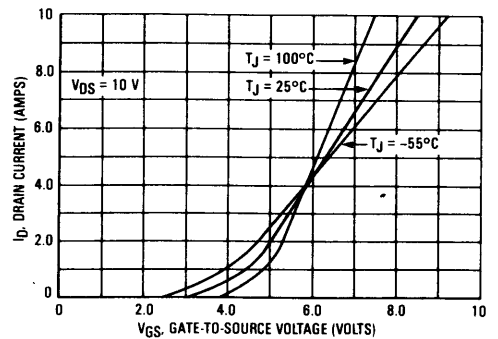


FIGURE 6 — MTM7N12, MTM7N15
MTP7N12, MTP7N15



ON-RESISTANCE versus DRAIN CURRENT

FIGURE 7 — MTM5N18, MTM5N20
MTP5N18, MTP5N20

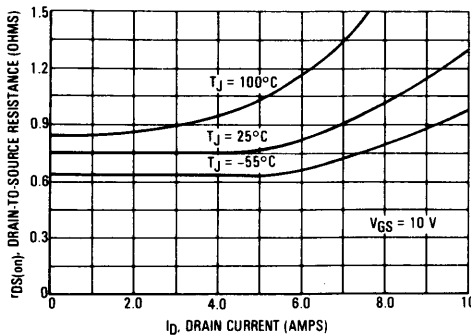
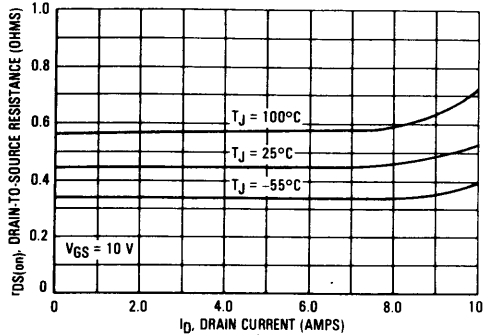


FIGURE 8 — MTM7N12, MTM7N15
MTP7N12, MTP7N15



TYPICAL CHARACTERISTICS

FIGURE 9 — GATE-THRESHOLD VOLTAGE VARIATION WITH TEMPERATURE

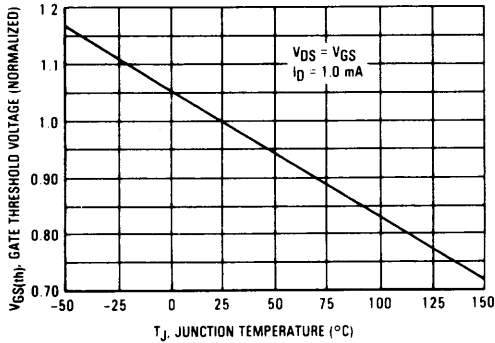
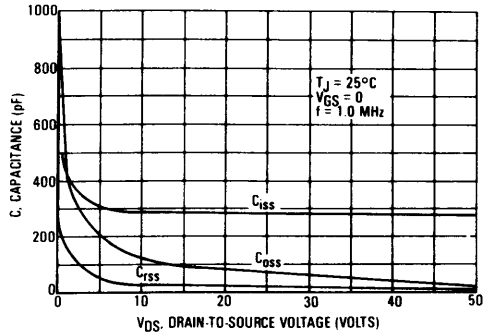


FIGURE 10 — CAPACITANCE VARIATION



THERMAL RESPONSE

FIGURE 11 — MTM7N12, MTM7N15, MTM5N18 AND MTM5N20

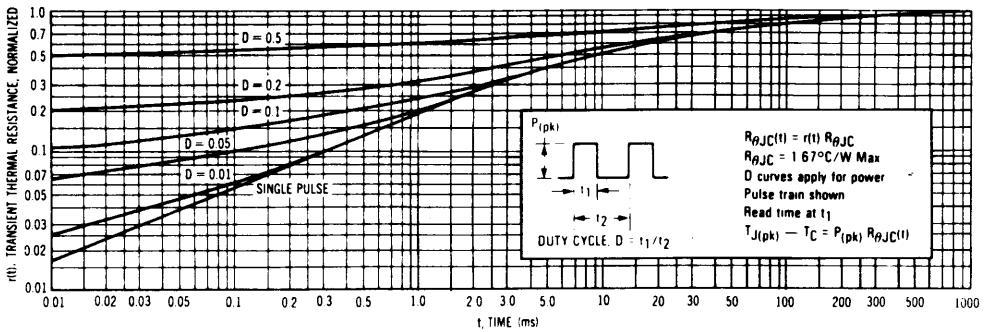
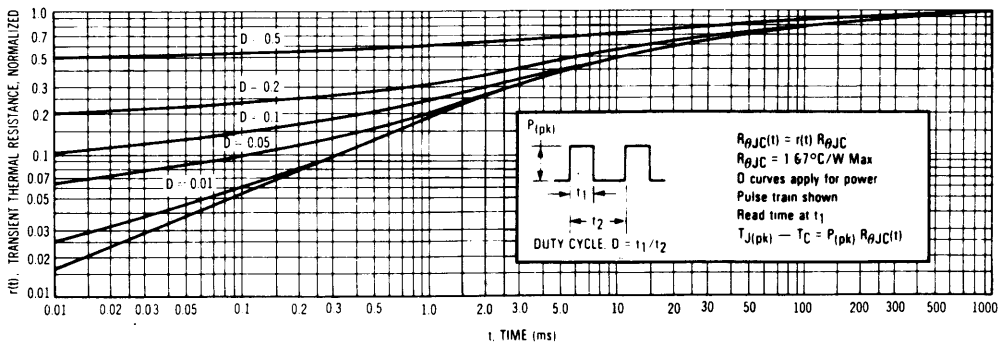


FIGURE 12 — MTP7N12, MTP7N15, MTP5N18 AND MTP5N20

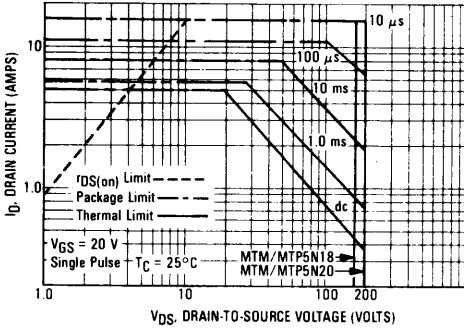


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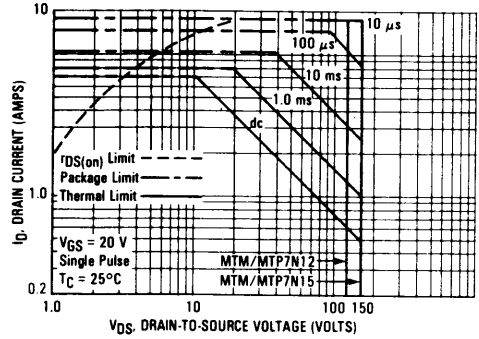
SAFE OPERATING AREA INFORMATION

MAXIMUM RATED FORWARD BIASED SAFE OPERATING AREA

**FIGURE 13 — MTM5N18, MTM5N20
MTP5N18, MTP5N20**



**FIGURE 14 — MTM7N12, MTM7N15
MTP7N12, MTP7N15**



FORWARD BIASED SAFE OPERATING AREA

The dc data of Figures 13 and 14 is based on a case temperature (T_C) of 25°C and a maximum junction temperature ($T_{J(max)}$) of 150°. The actual junction temperature depends on the power dissipated in the device and its case temperature. For various pulse widths, duty cycles, and case temperatures, the peak allowable drain current (I_{DM}) may be calculated with the aid of the following equation:

$$I_{DM} = I_D(25^\circ C) \left[\frac{T_{J(max)} - T_C}{P_D \cdot R_{\theta JC} \cdot r(t)} \right]$$

where

- $I_D(25^\circ C)$ = the dc drain current at $T_C = 25^\circ C$ from Figures 13 and 14.
- $T_{J(max)}$ = rated maximum junction temperature.
- T_C = device case temperature.
- P_D = rated power dissipation at $T_C = 25^\circ C$.
- $R_{\theta JC}$ = rated steady state thermal resistance
- $r(t)$ = normalized thermal response from Figures 11 and 12.

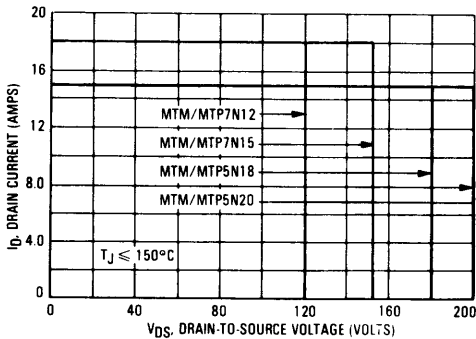
SWITCHING SAFE OPERATING AREA

The switching safe operating area (SOA) of Figure 15, is the boundary that the load line may traverse without incurring damage to the MOSFET. The fundamental limits are the peak current, I_{DM} and the breakdown voltage, $V_{(BR)DSS}$. The switching SOA shown in Figure 15 is applicable for both turn-on and turn-off of the devices for switching times less than one microsecond.

The power averaged over a complete switching cycle must be less than:

$$\frac{T_{J(max)} - T_C}{R_{\theta JC}}$$

**FIGURE 15 — MAXIMUM RATED SWITCHING
SAFE OPERATING AREA**



TMOS SOURCE TO DRAIN DIODE CHARACTERISTICS

In the fabrication of a TMOS FET, a diode is formed across the source-to-drain terminals as shown in Figure 16. Reversal of the drain voltage will cause current flow in the reverse direction. This

diode may be used in circuits requiring external fast recovery diodes, therefore, typical characteristics of the on voltage, forward turn-on and reverse recovery times are given.

FIGURE 16 — TMOS FET WITH SOURCE-TO-DRAIN DIODE

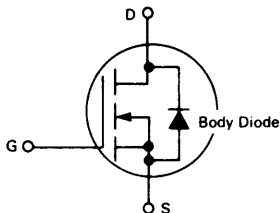


FIGURE 18 — BODY DIODE TURN-ON WAVEFORMS

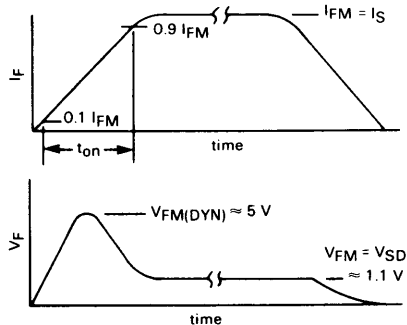


FIGURE 17 — DIODE TURN-ON TEST CIRCUIT

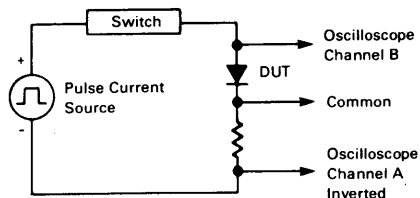


FIGURE 19 — REVERSE RECOVERY CHARACTERISTIC

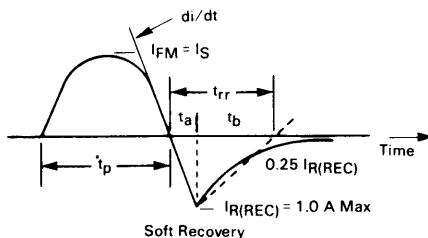


FIGURE 20 — JEDEC REVERSE RECOVERY CIRCUIT

